

IN THE CLAIMS:

Please cancel Claims 1 to 4, 7, 10 and 11 without prejudice or disclaimer of the subject matter presented therein and without conceding the correctness of their rejections. Please amend Claims 5, 6, 8 and 9 as shown below. The claims, as pending in the subject application, read as follows:

*Sub P3*  
1 to 4. (Cancelled)

5. (Currently Amended) ~~A semiconductor~~ An image pickup apparatus comprising:  
a lead of a flexible wiring ~~film~~; film;  
~~a semiconductor device~~ an image pickup element chip electrically connected to the ~~lead~~, lead at an electrical connection point; and  
a protecting member cover glass for protecting a surface of the ~~semiconductor device~~ image pickup element chip, which  
wherein the lead, the image pickup element chip, and the cover glass are sealed with ~~a sealant~~ an ultraviolet-curing resin in a peripheral portion of ~~said~~ ~~semiconductor device~~ the image pickup element chip, and  
wherein said the lead has a hole formed in a portion of the lead in contact with the ultraviolet-curing resin, the portion of the lead being between the electrical connection point and an outer end of the lead sealant.

*B1*

6. (Currently Amended) The semiconductor image pickup apparatus according to Claim 5, wherein at least a part of said the hole is formed in a region where a portion of the lead is sandwiched between said semiconductor device chip and said protecting member disposed between the cover glass and the ultraviolet-curing resin.

7. (Cancelled)

8. (Currently Amended) The semiconductor image pickup apparatus according to Claim 5, wherein at least one of a layer for preventing reflection of external light and a layer for preventing multiple reflection is formed between said the lead and said protecting member the cover glass.

9. (Currently Amended) An image pickup system comprising:  
a solid-state image pickup apparatus consisting of the semiconductor apparatus as set forth in either one of Claims 5 to 8 the image pickup apparatus according to Claim 5;

an optical system for focusing light on said solid-state the image pickup apparatus; and

a signal processing circuit for processing an output signal from said solid state the image pickup apparatus.

10 and 11. (Cancelled)